Power GaN Cascode Transistor 600 V, 150 m Ω

Features

- Fast Switching
- Extremely Low Q_{rr}
- Transphorm Inside
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

ABSOLUTE MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter			Symbol	NDD	Unit
Drain-to-Source Voltage			V_{DSS}	600	V
Gate-to-Source Volta	Gate-to-Source Voltage			±18	V
Continuous Drain	Steady State	T _C = 25°C	I _D	17	Α
Current R _{θJC}	State	T _C = 100°C		12	
Power Dissipation – R _{0JC}	Steady State	T _C = 25°C	P _D	96	W
Pulsed Drain Current	t _p = 10 μs		I _{DM}	60	Α
Operating Junction and Storage Temperature		T _J , T _{STG}	-55 to +150	°C	
Lead Temperature for Soldering Leads		T _L	260	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE

Parameter	Symbol	Value	Unit
Junction-to-Case (Drain)	$R_{\theta JC}$	1.55	°C/W
Junction-to-Ambient Steady State	$R_{\theta JA}$	62	°C/W

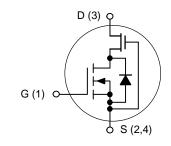


ON Semiconductor®

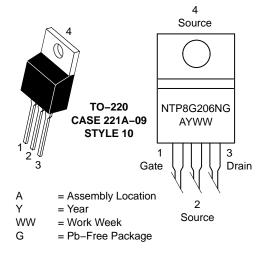
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V _{(BR)DSS}	R _{DS(ON)} TYP
600 V	150 mΩ @ 10 V

N-Channel MOSFET



MARKING DIAGRAM & PIN ASSIGNMENT



ORDERING INFORMATION

Device	Package	Shipping
NTP8G206NG	TO-220 (Pb-Free)	50 Units / Rail

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Characteristic	Symbol	Test Conditions		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$		600			V
Drain-to-Source Leakage Current	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	$T_J = 25^{\circ}C$		2.5	90	μΑ
			T _J = 150°C		8.0		
Gate-to-Source Leakage Current	I _{GSS}	$V_{GS} = \pm 18 \text{ V}$				±100	nA
ON CHARACTERISTICS (Note 1)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{DS} = V_{GS}, I_{D} = 500$) μΑ	1.6	2.1	2.6	V
Static Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = 8 \text{ V}, I_D = 11 \text{ A}, T_J$	= 25°C		150	180	mΩ
		V _{GS} = 8 V, I _D = 11 A, T _J	= 175°C		340		
DYNAMIC CHARACTERISTICS							
Input Capacitance	C _{iss}				760		pF
Output Capacitance	C _{oss}	V _{DS} = 480 V, V _{GS} = 0 V, f = 1 MHz			44		
Reverse Transfer Capacitance	C _{rss}				5.0		1
Effective output capacitance, energy related (Note 3)	C _{o(er)}	$V_{GS} = 0 \text{ V}, V_{DS} = 0 \text{ to } 480 \text{ V}$			64		
Effective output capacitance, time related (Note 4)	C _{o(tr)}	I_D = constant, V_{GS} = 0 V, V_{DS} = 0 to 480 V			105		
Total Gate Charge	Qg	V _{DS} = 100 V, I _D = 11 A, V _{GS} = 4.5 V			6.2	9.3	nC
Gate-to-Source Charge	Q _{gs}				2.1		1
Gate-to-Drain Charge	Q _{gd}				2.2		1
SWITCHING CHARACTERISTICS (Not							
Turn-on Delay Time	t _{d(on)}				6.2		ns
Rise Time	t _r	V_{DD} = 480 V, I_{D} = 11 A, V_{GS} = 10 V, R_{G} = 2 Ω			4.5		1
Turn-off Delay Time	t _{d(off)}				9.7		1
Fall Time	t _f				4.0		1
SOURCE-DRAIN DIODE CHARACTER	RISTICS						
Diode Forward Voltage	V_{SD}	I _S = 11 A, V _{GS} = 0 V	T _J = 25°C		2.2		V
Reverse Recovery Time	t _{rr}	V _{GS} = 0 V, V _{DD} = 400 V			17		ns
Reverse Recovery Charge	Q _{rr}	$I_S = 11 \text{ A, } d_i/d_t = 2000 \text{ A/}\mu\text{s}$			53		nC

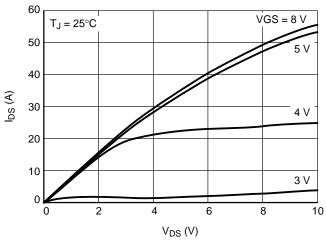
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Width $\leq 300~\mu s$, Duty Cycle $\leq 2\%$.

2. Switching characteristics are independent of operating junction temperatures.

3. $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% $V_{(BR)DSS}$ 4. $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% $V_{(BR)DSS}$

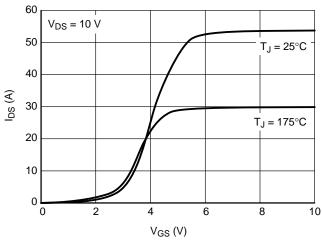
TYPICAL CHARACTERISTICS



40 35 30 25 20 15 10 5 0 0 2 4 6 8 10 VGS = 8 V 4 V 2 V 2 V 2 V 2 V 2 V 3 V 3 V 4 V

Figure 1. Typical Output Characteristics

Figure 2. Typical Output Characteristics



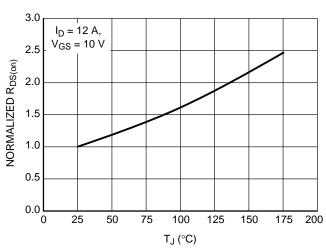
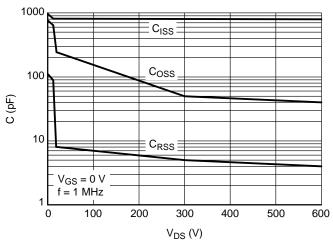


Figure 3. Typical Transfer Characteristics

Figure 4. Normalized On-Resistance



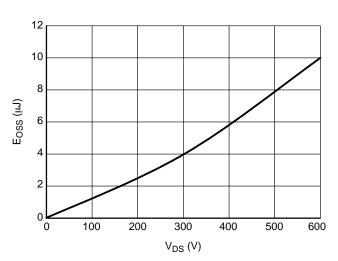


Figure 5. Typical Capacitance

Figure 6. Typical C_{OSS} Stored Eneergy

TYPICAL CHARACTERISTICS

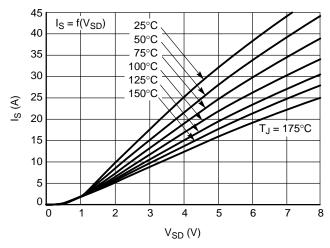


Figure 7. Forward Characteristics of Rev. Diode

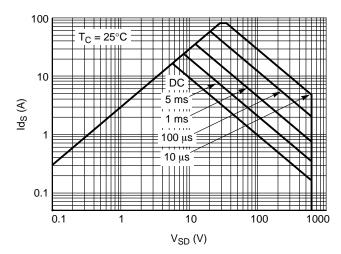


Figure 8. Safe Operating Area

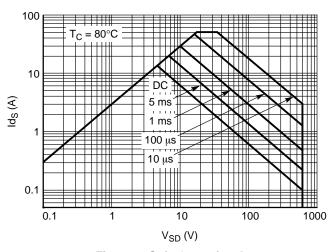


Figure 9. Safe Operating Area

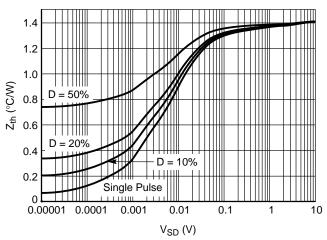


Figure 10. Transient Thermal Resistance

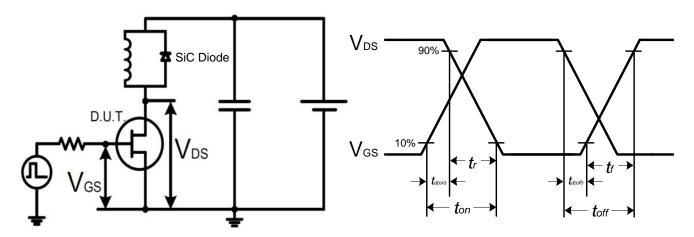


Figure 11. Switching Time Test Circuit

Figure 12. Switching Time Waveform

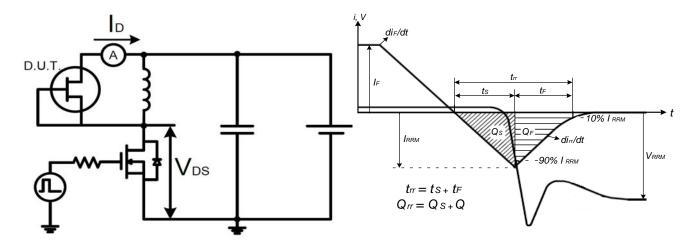
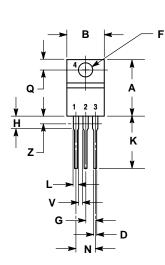


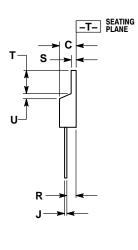
Figure 13. Test Circuit for Reverse Diode Characteristics

Figure 14. Diode Recovery Waveform

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AH**





- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIN	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX		
Α	0.570	0.620	14.48	15.75		
В	0.380	0.415	9.66	10.53		
С	0.160	0.190	4.07	4.83		
D	0.025	0.038	0.64	0.96		
F	0.142	0.161	3.61	4.09		
G	0.095	0.105	2.42	2.66		
Н	0.110	0.161	2.80	4.10		
J	0.014	0.024	0.36	0.61		
K	0.500	0.562	12.70	14.27		
L	0.045	0.060	1.15	1.52		
N	0.190	0.210	4.83	5.33		
Q	0.100	0.120	2.54	3.04		
R	0.080	0.110	2.04	2.79		
S	0.045	0.055	1.15	1.39		
Т	0.235	0.255	5.97	6.47		
U	0.000	0.050	0.00	1.27		
٧	0.045		1.15			
Z		0.080		2.04		

STYLE 10:

PIN 1. GATE

- 2. SOURCE
- DRAIN
- 3.

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